

# **SELECTION GUIDE**



## HAMAMATSU

# **OVERVIEW**

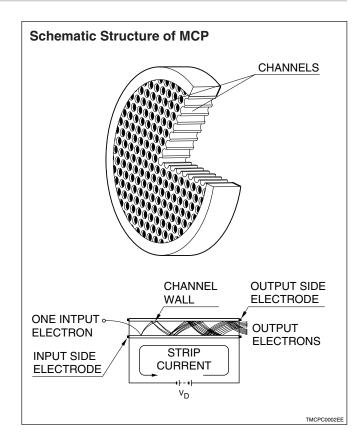
MCP (microchannel plate) is a two-dimensional sensor that detects electrons, ions, vacuum UV rays, X-rays and gamma rays, and amplifies the detected signals. Circular and rectangular MCPs are available in various dimensions, including easy-to-use MCP assemblies with pre-mounted electrode leads and supports. These MCPs are widely used in many types of analytical equipment such as for "mass spectroscopy", "semiconductor inspection" and "surface analysis".

The MCP assemblies are available with three different readout devices to meet application needs. The devices are of: (1) single anode (electrical output signal measurement within effective region), (2) multianode (electrical output signal measurement corresponding to signal input positions), and (3) phosphor screen (optical imaging of output signal). Select the output device that best matches your application.

From one to three stage MCPs can be selected for the assembly to obtain necessary gain, allowing uses in the analog mode (the output signal is measured as a continuous electrical current) or the counting mode (the low level signal can be measured by a binary processing).

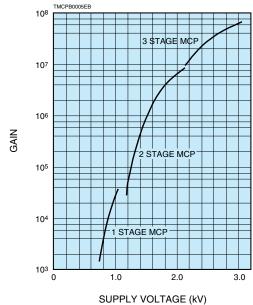
# **OPERATING PRINCIPLE**

As shown in the figure on the right, a potential gradient is established along the channel when the voltage V<sub>D</sub> is applied between the input and output sides of the MCP. Multiple secondary electrons are emitted when an electron enters a channel from the input side and strikes its inner wall. These secondary electrons are accelerated by the potential gradient to draw parabolic trajectories that are determined by their initial velocities. They then strike the opposite wall in the channel causing further secondary electrons to be emitted. The electrons in this way travel towards the output end while striking the inner wall of the channel repeatedly. As a result, a large number of exponentially increased electrons are extracted from the output side.



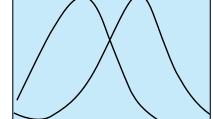
# **CHARACTERISTCS**

### MCP Gain Characteristics



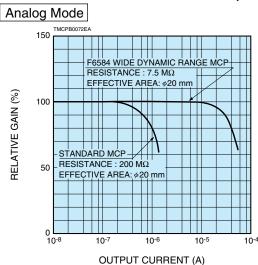
TMCPB0034ED NUMBER OF COUNTS (S-1) 2 STAGE MCP 3 STAGE MCP

■Pulse Height Distribution (PHD)

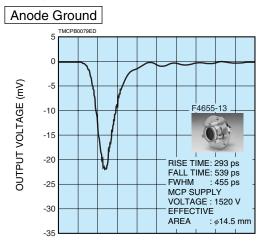


PULSE HEIGHT (CHANNEL NUMBER)

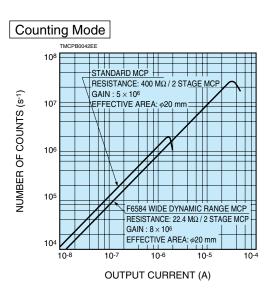
## **MCP** Saturation Characteristics (Output Linearity)

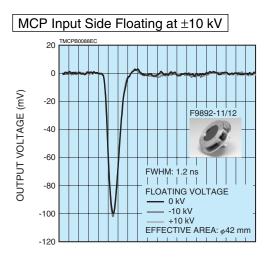


## Output Waveform



RESPONSE TIME (500 ps/div.)

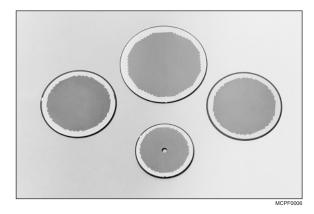


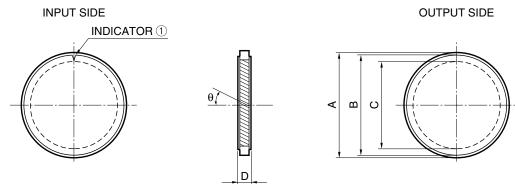


RESPONSE TIME (1 ns/div.)

## **BARE MCP** dimensions and specifications

## Circular MCP (Bare MCP)





TMCPA0056EA

Туре	F1551-01	F10	)94 <sup>②</sup>	F6584-01	F1	552 <sup>②</sup>	E1208-01	E1217_01	F1942-04	E2205-04	Unit
Parameter	F1551-01	-01	-09	F0304-01	-01	-09	F1200-01	F1217-01	F1342-04	F2395-04	Onit
Outer Size A	φ17.9		<i>φ</i> 24.8			2.8	ø38.4	φ49.9	<i>φ</i> 86.7	<i>φ</i> 113.9	mm
Electrode Area B	φ17		ø23.9		φ3	1.8	ø36.5	<i>φ</i> 49	φ84.7	ø112	mm
Effective Area C	φ14.5		φ20			27	φ32 φ42		φ77	ø105	mm
Thickness D	0.48	0.48	0.48 0.41 0.48			0.41	0.	48	1.	00	mm
Channel Diameter	12	12	10	12	12	10	1	2	2	5	μm
Channel Pitch	15	15	12	15	15	12	1	5	3	1	μm
Bias Angle θ	8	8 5 8 8,12 8									degrees
Open Area Ratio					6	60					%
Electrode Material					Inco	onel					—
Gain (Min.) <sup>5</sup>					1	04					—
Resistance 5	100 to 700	50 to	500	2 to 30	30 to	008 0	20 to 200	10 to 200	10 to 100	5 to 50	MΩ
Dark Current (Max.) <sup>(5)</sup>		0.5								pA⋅cm <sup>-2</sup>	
Maximum Linear Output <sup>(5)</sup>		7 % of Strip Current <sup>④</sup>								—	
Supply Voltage 6		1.0								kV	
Operating Ambient		-50 to +70									
Temperature 6					-50 10	0 +70					°C

**NOTE:** 1)This mark indicates the MCP input side.

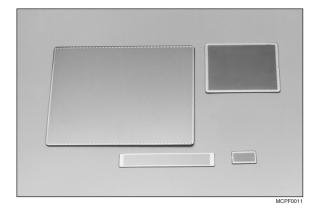
2 Variant types with 6 μm channel diameter are also available.

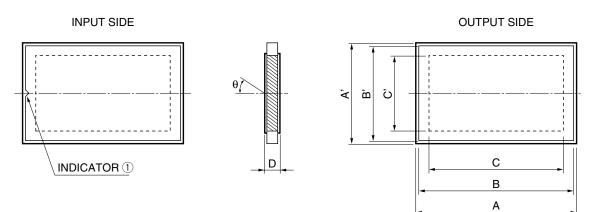
③Wide dynamic range type designed to obtain high output current. (See the graph "MCP Saturation Characteristics" on page 2.)

(4) The strip current is an electric one that flows along channel walls when a voltage is applied between MCP IN and OUT. This is obtained by dividing the applied voltage by the MCP plate resistance. (5) Supply voltage: 1.0 kV, vacuum: 1.3×10<sup>-4</sup> Pa, operating ambient temperature: +25 °C

6 Vacuum: 1.3×10-4 Pa

# Rectangular MCP (Bare MCP)





TMCPA0057EA

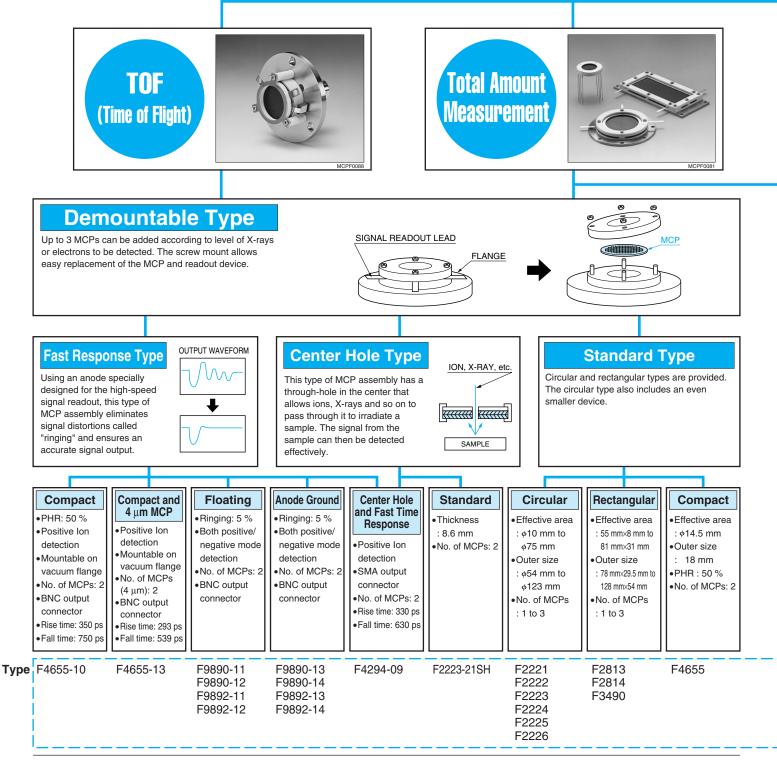
Type Parameter	F6492	F2370-01	F4772-01	F2806-01	F1943-02	F2805-03	F2396-04	Unit		
Outer Size A×A'	139.9×8.9	15.9×9.4	61.9×13.9	49.9×39.9	87.9×37.9	59.9×59.9	96.9×78.9	mm		
Electrode Size B×B'	138×8	15×8.5	61×13	49×39	87×37	58×58	95.6×77.3	mm		
Effective Area C×C'	127×4	13×6.5	55×8	45×35	81×31	53×53	90×72	mm		
Thickness D		0.48 0.60 0.80 1.00								
Channel Diameter		12 15 20 25								
Channel Pitch		15 19 25 31								
Bias Angle θ		8								
Open Area Ratio		60								
Electrode Material				Inconel				]		
Gain (Min.) <sup>5</sup>				104				—		
Resistance <sup>5</sup>	5 to 50	20 to 120		20 to	200		100 to 500	MΩ		
Dark Current (Max.) <sup>5</sup>		0.5								
Maximum Linear Output <sup>5</sup>		7 % of Strip Current <sup>@</sup>								
Supply Voltage 6		1.0								
Operating Ambient Temperature <sup>6</sup>		-50 to +70								

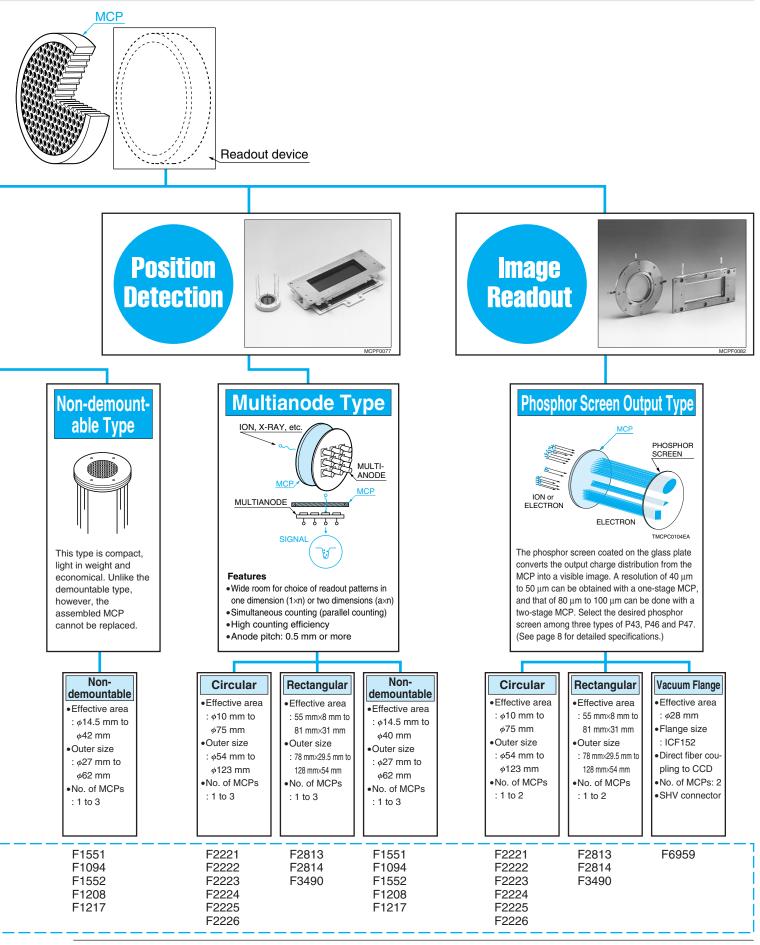
# **MCP ASSEMBLY SELECTION GUIDE BY PURPOSE**

MCP is a two-dimensional sensor that detects electrons, ions, X-rays and so on, and multiplies the detected signals with high efficiency, high speed and thus resulting high temporal resolution. This selection guide would help you choose the best MCP assembly that has a suitable readout configuration for your application.

### What do you want to detect?

- +/- lon
- Electron
- • X-ray
- High energy particle
  ••••••••





# MCP ASSEMBLY SELECTION GUIDE BY APPLICATIONS

Major applications of MCP assemblies include "mass spectroscopy", "semiconductor inspection" and "surface analysis". The table below gives you a quick reference for selecting the best MCP assembly in these major application fields. This table shows only typical applications. Feel free to contact our sales office in your area if you do not find your specific application here.

$\searrow$	Field		Mass spectroscopy					ру	Semiconductor inspection				n Surface analysis													
Detection method	Application MCP assembly	Time-of-flight mass spectroscopy (TOF-MS) (MALDI)	Time-of-flight mass spectroscopy (TOF-MS) (LC-MS)	Quadrupole mass spectroscopy (Q-MS)	Double focusing mass spectroscopy (Sector-MS)	Gas or liquidchromatographic mass spectroscopy (GC/LC-MS)	Inductive-coupled plasma mass spectroscopy (ICP-MS)	Secondary ion mass spectroscopy (SIMS)	Scanning electron microscope (SEM)	Scanning ion microscope (SIM)	Electron beam measuring system (EBMS)	Electron or ion beam lithography	Mask aligner	FIB system	Auger electron spectroscopy (AES)	Ion scattering spectroscopy (ISS)	Electron spectroscopy for chemical analysis (ESCA)	Rutherford backscattering spectroscopy (RBS)	Vacuum UV spectroscopy (VUVS)	Soft X-ray spectroscopy (SXS)	Reflection medium energy electron diffraction (RMEED)	Low energy electron diffraction (LEED)	Field ion microscope (FIM)	Tranmission electron microscope (TEM)	Soft X-ray microscope (SXM)	Positron detector
	Demountable, circular MCP assembly (single anode)	0	0	$\bigcirc$	0	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	0	$\bigcirc$		$\bigcirc$	0	$\bigcirc$	$\bigcirc$										
TOF	Demountable, rectangular MCP assembly (single anode)	0	0	0	0										0	0										
nt, T(	Non-demountable, circular MCP assembly (single anode)	0	0	0	0	0	0	$\bigcirc$	$\bigcirc$	0	0				$\bigcirc$	0										
eme	F2223-21SH	0	0						$\bigcirc$	$\bigcirc$	$\bigcirc$	$\odot$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\odot$										
Total Amount measurement,	F4294-09	0	$\odot$							$\bigcirc$	0			$\bigcirc$	$\odot$	$\odot$										
nt me	F4655														0	0										
nour	F4655-10	0	0	$\odot$	0	0	$\odot$	$\bigcirc$							0	0										
tal A	F4655-13	0	$\odot$	0	0			0							$\bigcirc$	0										
To	F9890-11/-12, F9892-11/-12	0	$\odot$	$\odot$	0	$\odot$	$\odot$	$\bigcirc$							0	0										
	F9890-13/-14, F9892-13/-14	0	0	$\odot$	0	0	0	0							0	0										
mage readout Position detection	Demountable, circular MCP assembly (multi-anode)	0	0	$\bigcirc$	0	0	0	$\bigcirc$									$\odot$		0	$\bigcirc$						
on det	Demountable, rectangular MCP assembly (multi-anode)	0	0		0			$^{\circ}$									$\odot$	0	0	0						
Positi	Non-demountable, circular MCP assembly (multi-anode)				0			$\bigcirc$									$\odot$		0	$\bigcirc$						
adout	Demountable, circular MCP assembly (phosphor screen)				0			$\bigcirc$											$\odot$	$\odot$	$\odot$	$\odot$	O	0	0	$\bigcirc$
ge rea	Demountable, rectangular MCP assembly (phosphor screen)																		$\odot$	$\odot$	0	0	0	0	0	$\bigcirc$
Ima	F6959																		$\odot$	$\odot$	0	$\bigcirc$	0	0	$\bigcirc$	$\bigcirc$

# **MCP ASSEMBLY SPECIFICATIONS**

Assembly Type	Circular	Rectangular	Circular	Center Hole	Fast Response with Center	Center	Compact	1 Compact, Fast Response	① Compact, Fast Response, 4 μm	for ± Dete	(1) esponse Mode ction, ating	Fast Re for ± I Detec Anode 0	Mode ction,	1 Phosphor Screen Output with Vacuum	Unit
Type No.	Demou	untable	Non- demountable	F2223-21SH	Hole F4294-09	Hole F6589	F4655	F4655-10	MCP			F9890-13 F9892-13		Flange F6959	-
Outer Size	φ54 to φ123	78×29.5 to 128×54	φ27 to φ62	φ56.5			ø18	φ38		F9890 series: φ81 F9892 series: φ92				¢152	mm
Effective Area	φ10 to φ75	55×8 to 81×31	¢14.5 to φ42	φ2	φ27      φ11      φ14.5      F9890 series: φ27 F9892 series: φ42							φ28	mm		
Height	15 to 17	10.9 to 12.9	4.5 to 5.7	8.6	17	2.5	8.5	31	1.9	54.1	53.7	33.3	32.9	36.1	mm
Number of MCPs	With Phosphor	1 to 3 Screen: 1 to 2							2						—
MCP Center Dead Area		—		φ8	φ12	φ4		—							mm
Gain <sup>3</sup>	2 stage	e MCP: 10 e MCP: 10 e MCP: 10	0 <sup>6</sup> Min.		10 <sup>6</sup> Min.		5 × 10 <sup>7</sup> Min. 10 <sup>6</sup> Min.							—	
Pulse Height Resolution <sup>③</sup> (FWHM) (Max.)		ge MCP: ge MCP:			_		5	0	120		1	50		120	%
Dark Count (Max.) <sup>3</sup>		r 3 stage	,			3			5			3			s <sup>-1</sup> ·cm <sup>-2</sup>
MCP Supply Voltage <sup>(4)</sup>	2 st 3 st	tage MCF tage MCF tage MCF	2:0 2:3.0		2.0		2	.5			2	.0			kV
MCP-OUT to Anode Supply Voltage <sup>(4)</sup>	Single Multia Phosphor scre		: 0.5 : 0.5	. 0	.5	0.4	0.5 3.0						3.0	kV	

NOTE: 1) Vacuum baking cannot be performed on these MCP assemblies.

2 Phosphor screen type is not available.

3Supply voltage: 1.0 kV/MCP, vacuum: 1.3×10<sup>-4</sup> Pa, operating ambient temperature: +25 °C 4Vacuum: 1.3×10<sup>-4</sup> Pa

4 vacuum: 1.3×10 <sup>4</sup> Pa

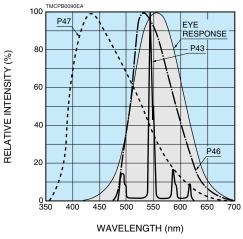
## PHOSPHOR SCREEN

Select the desired phosphor screen by taking into account the afterglow time according to the readout method and application, and the emission wavelength according to the readout device sensitivity.

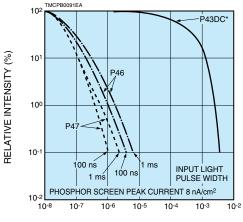
Phosphor Screen Type	Peak Emission Wavelength (nm)	Emission Color	Relative Energy Efficiency <sup>(5)</sup>	10 % Afterglow Time	Remarks
P43	545	Yellowish Green	1	1 ms	Standard Type
P46	530	Yellowish Green	0.3	0.2 $\mu s$ to 0.4 $\mu s$ $^{\odot}$	Short Afterglow
P47	430	Purplish Blue	0.3	0.11 μs	Very Short Afterglow

NOTE: (5)Supply voltage: 6 kV. Value relative to P43 which is specified as 1. (6)Varies depending on the input pulse width.

## Spectral Emission Characteristics



## ■Afterglow Characteristics



AFTERGLOW TIME (s) \* Afterglow characteristics after removal of continuous light input

# MCP ASSEMBLY DIMENSIONAL OUTLINES

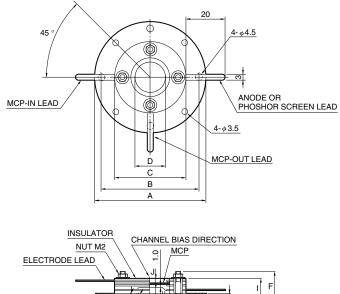
Total Amount Measurement

) ( Image

## **Circular MCP Assembly (Demountable)**

Position

Detection



CHANNEL BIAS DIRECTION	
NUT M2 OI MCP	
→ G →	
TMC	PA0026EF



Anode Type	No. of MCPs
Single anode	1 to 3
Multianode	1 to 3
Phosphor screen	1 to 2

Symbol	Description	n		F2221	F2222	F2223	F2224	F2225	F2226	Unit
A	Assembly outer si	ze		<i>φ</i> 54	<i>φ</i> 61	<i>φ</i> 69	φ75	<i></i> \$86	ø123	mm
В	Mounting screw ho	rew hole pitch			<i>φ</i> 53	<i>φ</i> 61	$\phi 67$	φ78	φ115	mm
С	Insulator outer siz	e		<i>φ</i> 34	<i>φ</i> 41	<i>φ</i> 49	$\phi 55$	<i></i> \$66	<i>φ</i> 103	mm
D	Effective area of N	ИCР		ø14.5	<i>φ</i> 20	φ27	φ32	<i>φ</i> 42	φ77	mm
E	Effective area of read	out dev	/ice	φ10	φ17	<i>φ</i> 24	φ30	<i>φ</i> 40	φ75	mm
F	Maximum height	aximum height			15	15	15	15	17	mm
G	Replacement ring	acement ring screw		M21	M28	M35	M42	MEO	M00	
G	size for readout d	evice			11/28	11135	IVI42	M52	M89	-
Н	Replacement ring	insid	inside		400	407	400		4 70	
^	size for readout d	evice		<i>φ</i> 13	<i>φ</i> 20	φ27	<i></i> \$33	<i></i> \$44	<i>φ</i> 78	mm
	Distance from	No.	1			10.9			12.9	
1	bottom of substrate of 2					11.9			14.4	mm
	to insulator surface	urface MCPs 3			11.9					
	Distance from MCP	No.	1			2.8			3.8	
J	input surface to	of 2					4.3	mm		
	insulator surface	MCPs	3			2.9			4.8	

\* This dimension shows for a Phosphor read out type. Other read out type may have a different dimension from it.

(For further details, please consult with us.)

#### MCP-OUT LEAD 3 CHANNEL BIAS DIRECTION MCP-IN LEAD 20 ۲ Ć ۲ B' D' Α ه ک ۲ ANODE OR PHOSPHOR SCREEN 4- ø3.5 D LEAD ELECTRODE С LEAD в Α MCP SCREW M2 INSULATOR G, SUBSTRATE ო F DEGASSING SPACE READ-OUT DEVICE

**Rectangular MCP Assembly (Demountable)** 

Anode Type	No. of MCPs
Single anode	1 to 3
Multianode	1 to 3
Phosphor screen	1 to 2

<b></b>							
Symbol	Descriptior	۱		F2813	F2814	F3490	Unit
A×A'	Assembly outer size			128×54	96×76	78×29.5	mm
B×B'	Mounting screw hole	e pitch		120×46	86×68	72×18	mm
C×A'	Insulator outer size			104×54	76×76	66×29.5	mm
D×D'	Effective area of MC		81×31	53×53	55×8	mm	
E×E'	Effective area of read	/ice	80×30	50×50	52×7	mm	
	Distance from	No.	1	10.9	10.9		
F	bottom of substrate	of	2	11.9	11.9	11.9	mm
	to insulator surface	MCPs	3	11.9	12.9		
	Distance from MCP	No.	1	2.7	2.5	3.8	
G	input surface to	of	2	3.1	2.7	3.3	mm
	insulator surface	MCPs	3	2.5	2.9	2.9	1

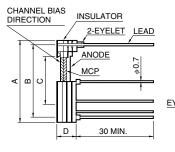
\* This dimension shows for a Phosphor read out type. Other read out type may have a different dimension from it.

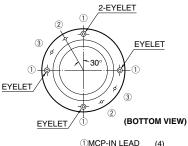
(For further details, please consult with us.)

TMCPA0029EF



## **Circular MCP Assembly (Non-demountable)**





①MCP-IN LEAD(4)②MCP-OUT LEAD(2)③ANODE LEAD(2)

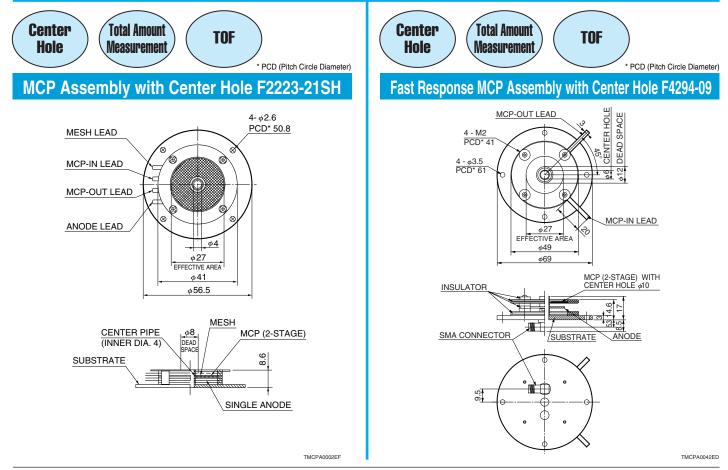
Anode Type	No. of MCPs
Single anode	1 to 3
Multianode	1 to 3

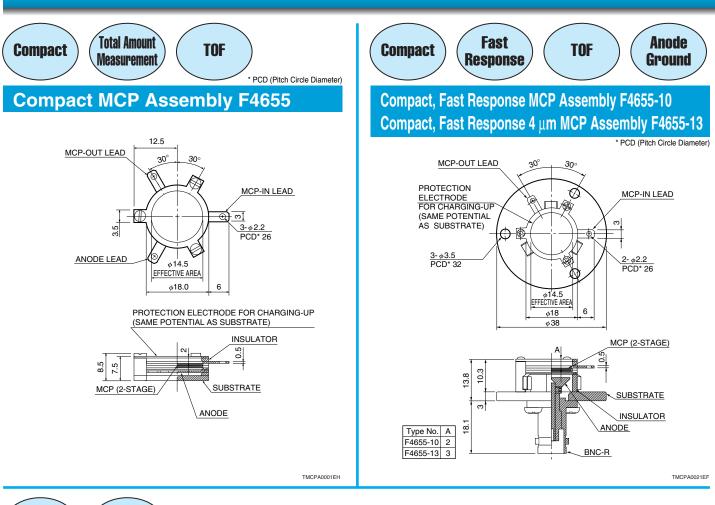
Symbol	Description			F1551	F1094	F1552	F1208	F1217	Unit
Α	Assembly outer size			φ27	<i>ø</i> 34	φ42	<i>φ</i> 49	<i>φ</i> 62	mm
В	Lead pin circle			φ22.5	φ29.5	φ37.5	<i>φ</i> 44	φ56	mm
С	Effective area			φ14.5	<i>φ</i> 20	φ27	<i>φ</i> 32	ø42	mm
D	Assembly height	No.	1	4.5					
		of	2	5.7					mm
		MCPs	3	5.7					

\* The dimensions of multianode types may differ.

No anode type is also available.

TMCPA0027ED



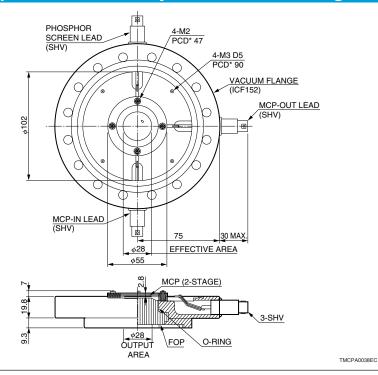


Fiber Coupling

Image

\* PCD (Pitch Circle Diameter)

## **Phosphor Screen Output MCP Assembly with Vacuum Flange F6959**



11

## MCP ASSEMBLY DIMENSIONAL OUTLINES

BACK VIEW

LEAD

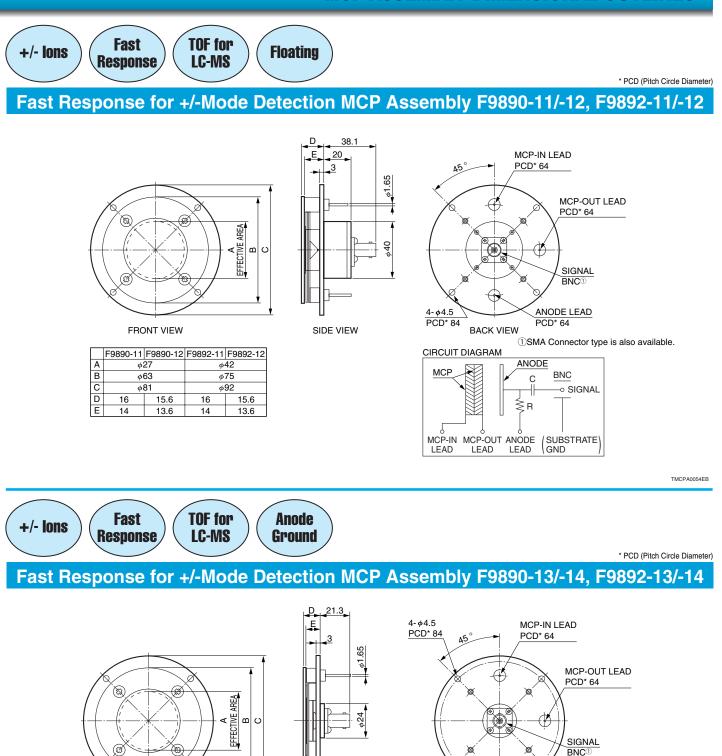
ANODE

CIRCUIT DIAGRAM

MCP

ľ MCP-IN MCP-OUT LEAD

1)SMA Connector type is also available.



SIDE VIEW

FRONT VIEW

φ27

*φ*63

φ81

10

11.6

9.6

A

В

С

D 12

Е

F9890-13 F9890-14 F9892-13 F9892-14

φ42

φ75

φ92

11.6

9.6

12

10

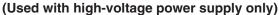
TMCPA0075EA

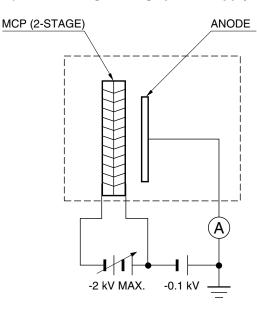
# MCP ASSEMBLY WIRING EXAMPLES

Any of the MCP-IN, MCP-OUT, anode and phosphor screen can be at ground potential.

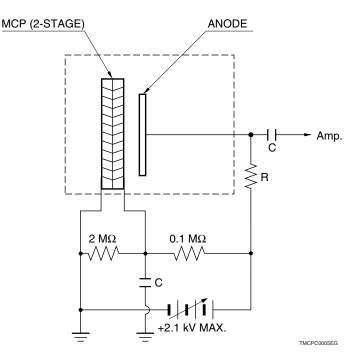
## **Signal Detection**

## Positive ion detection



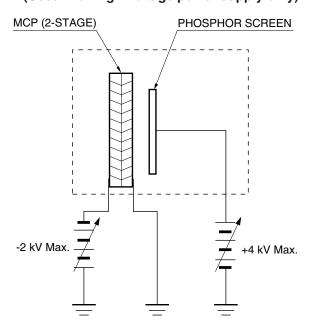


•Electron or negative ion detection (Used with high-voltage power supply and divider circuit)

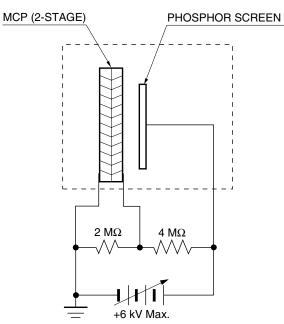


## **Image Detection**

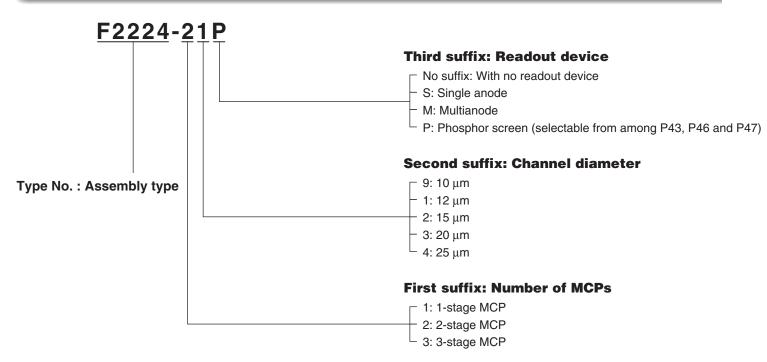
 Positive ion detection (Used with high-voltage power supply only)



•Electron or negative ion detection (Used with high-voltage power supply and divider circuit)



## **TYPE NUMBER DESIGNATION FOR PLACING ORDER\***



\* This ordering information applies ONLY to circular/rectangular MCP assemblies (demountable type) listed in the page 9 and circular/rectangular MCP assemblies (non-demountable type) listed in the page 10. Use their type numbers as listed when ordering other MCP assemblies and bare MCPs (non-assembled MCPs).

When the MCP assembly doesn't have the 3rd digit on the suffix, it means no signal collection anode as a factory set-up. In case of using a phosphor as an anode for the image or position detection, the special parts and treatment must be supplied. Please contact our office shown on the back cover at first.

# **CUSTOM DEVICES**

- •We also manufacture custom-designed MCPs and MCP assemblies not included in the standard product lineup. Please consult us with your specific requirements for outside dimensions, effective dimensions, thickness, etc.
- •Feel free to consult us on MCPs with a special aperture or through-hole (for use with reflection electron microscopes), CsI deposition (for higher quantum efficiency in the VUV to X-ray range), aluminum film coating (as a barrier to ions and radiation), MgO coating (for higher gain), electrodes made of Au (gold) and special-purpose MCPs.
- •For multianodes, consult us on the desired anode pattern.
- Assemblies with a phosphor-coated fiber optic plate (FOP) are available to enable fiber-coupling to solid state imaging devices (CCD, MOS linear image sensors), etc.
- Assemblies with an MCP, readout device and lead terminals mounted on a special vacuum flange or printed circuit board are also available.

# WARRANTY PERIOD AND COVERAGE

This product is warranted for a period of one year from the date of shipment. If you find any failure or defect in the workmanship and notify us within this warranty period, we will repair or replace it free of charge. The warranty is limited to replacement of the defective product.

Even if within the warranty period, this warranty shall not apply to failures or damages that were caused by the product reaching the end of its service life, incorrect operation, or accidents such as natural or man-made disasters.

### 1. STORAGE

The MCP and the MCP assembly are shipped in packages that are evacuated to a vacuum or filled with dry nitrogen. These packages are intended for use during shipping and not suited for long-term storage. When storing the MCP and MCP assemblies, take them out of their packages and keep them in a clean case under either a) or b) of the following conditions.

a) At vacuum pressure below 13 Pa and no oil diffusion.

b) Under gentle constant flow of dry nitrogen passed through a 0.45 µm or smaller filter (humidity: 20 % or less).

### 2. HANDLING

Avoid touching the MCP and the MCP assembly with bare hand. If handled with bare hand, these might be contaminated by oil and salt from it causing an increase in dark current, a loss of gain and an electrical discharge.

When handling them, always wear clean vinyl or polyethylene gloves. Even when you wear gloves, never touch the effective area of the MCP and the MCP assembly.

### 3. ENVIRONMENTS

The MCP surface is processed to be electrically active and the components used for the assembly are also processed for high vacuum use. So as much as possible, handle them in an environment conforming to clean-room (dust-proof room) specifications where oily vapor, moisture and dust are minimized.

If dusts or debris get on the MCP surface, blow them off with dry clean air or nitrogen gas. When doing this, check the pressure and surrounding area so as not to blow other dust into the air. Never use your own breath to blow off the dust from the MCP surface.

### 4. DEGASSING BEFORE USE

Gas adsorption usually occurs on the surface of an MCP which has not yet been used after delivery or has been stored after use. The MCP must be evacuated in a high vacuum below  $1.3 \times 10^{-4}$  Pa for more than 24 hours to perform degassing before using it (before supplying a voltage).

### 5. VACUUM BAKING

Vacuum baking is effective in degassing when the MCP or the MCP assembly is to be used in a high vacuum. Perform the vacuum baking under 150 °C while keeping the exhaust system at a vacuum pressure below  $1.3 \times 10^{-4}$  Pa. Vacuum baking cannot be performed on some types of MCP assembly. Please consult us for details.

### 6. SUPPLY VOLTAGE

Always maintain the MCP and the MCP assembly high vacuum condition below  $1.3 \times 10^{-4}$  Pa in operation. When supplying a voltage to the MCP or MCP assembly and to the output signal readout device (anode, phosphor screen), slowly increase it at every 100 V step (approx. 5 seconds per 100 V).

### 7. THE DISPOSAL METHOD

The materials in these products contain lead and its compound. Please follow the applicable regulations regarding disposal of hazardous materials and industrial wastes in your country, state, region or province.

Subject to local technical requirements and regulations, availability of products included in this promotional material may vary. Please consult with our sales office. Information furnished by HAMAMATSU is believed to be reliable. However, no responsibility is assumed for possible inaccuracies or omissions. Specifications are subject to change without notice. No patent rights are granted to any of the circuits described herein. ©2009 Hamamatsu Photonics K.K.



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